

POWER SCHOTTKY RECTIFIER

Table 1: Main Product Characteristics

$I_{F(AV)}$	2 A
V_{RRM}	60 V
$T_j(\text{max})$	150°C
$V_F(\text{max})$	0.55 V

FEATURES AND BENEFITS

- Negligible switching losses
- Low forward voltage drop
- Surface mount miniature package
- Avalanche capability specified

DESCRIPTION

Axial and Surface Mount Power Schottky rectifiers suited to Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in SMA and DO-41, this device is especially intended for use in low voltage, high frequency inverters and small battery chargers.

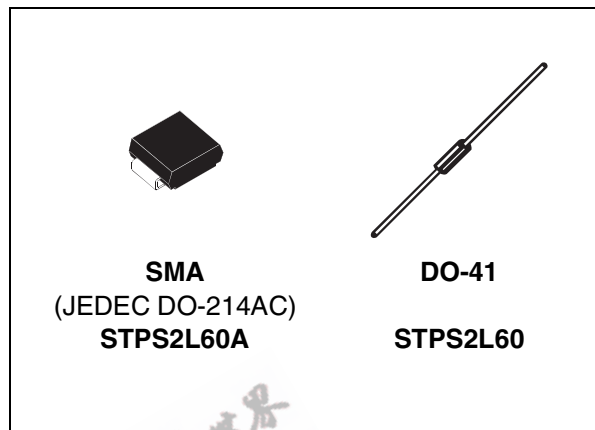


Table 2: Order Codes

Part Number	Marking
STPS2L60A	S26
STPS2L60	STPS2L60
STPS2L60RL	STPS2L60

Table 3: Absolute Ratings (limiting values)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		60	V
$I_{F(RMS)}$	RMS forward current		10	A
$I_{F(AV)}$	Average forward current	SMA	2	A
		DO-41		
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ms}$ sinusoidal	75	A
P_{ARM}	Repetitive peak avalanche power	$t_p = 1\mu\text{s} \quad T_j = 25^\circ\text{C}$	1600	W
T_{stg}	Storage temperature range		-65 to + 150	°C
T_j	Maximum operating junction temperature *		150	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/ μs

* : $\frac{dP_{tot}}{dT_j} > \frac{1}{R_{th(j-a)}}$ thermal runaway condition for a diode on its own heatsink

STPS2L60

Table 4: Thermal Resistance

Symbol	Parameter		Value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	25	$^{\circ}\text{C}/\text{W}$
		Lead length = 10 mm DO-41	30	

Table 5: Static Electrical Characteristics

Symbol	Parameter	Tests conditions		Min.	Typ	Max.	Unit
I_R^*	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			100	μA
		$T_j = 100^{\circ}\text{C}$			2	10	mA
V_F^{**}	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 2\text{A}$			0.60	V
		$T_j = 125^{\circ}\text{C}$			0.51	0.55	
		$T_j = 25^{\circ}\text{C}$	$I_F = 4\text{A}$			0.77	
		$T_j = 125^{\circ}\text{C}$			0.62	0.67	

Pulse test: * $t_p = 380 \mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation: $P = 0.43 \times I_{F(AV)} + 0.06 I_{F(RMS)}^2$

Figure 1: Average forward power dissipation versus average forward current

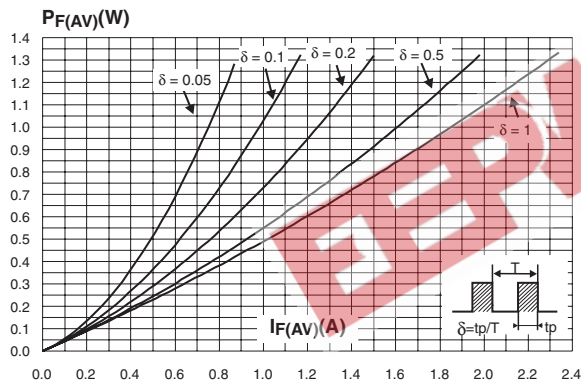


Figure 2: Average forward current versus ambient temperature (delta = 0.5)

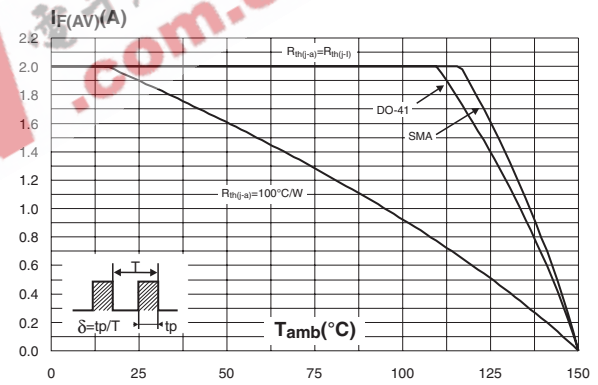


Figure 3: Normalized avalanche power derating versus pulse duration

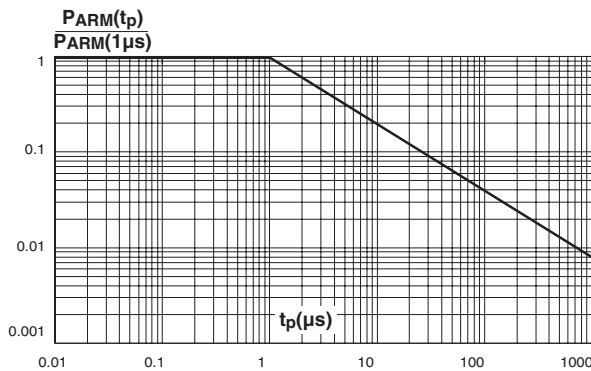


Figure 4: Normalized avalanche power derating versus junction temperature

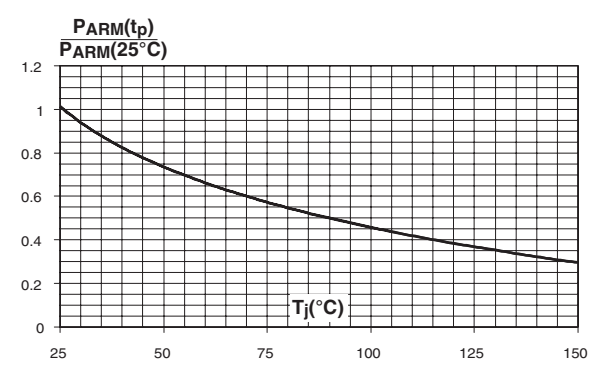


Figure 5: Non repetitive surge peak forward current versus overload duration (maximum values) (SMA)

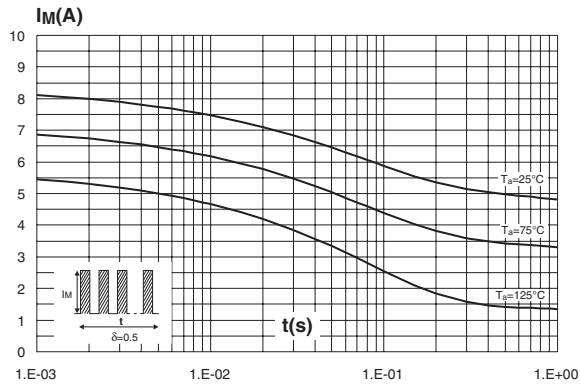


Figure 6: Non repetitive surge peak forward current versus overload duration (maximum values) (DO-41)

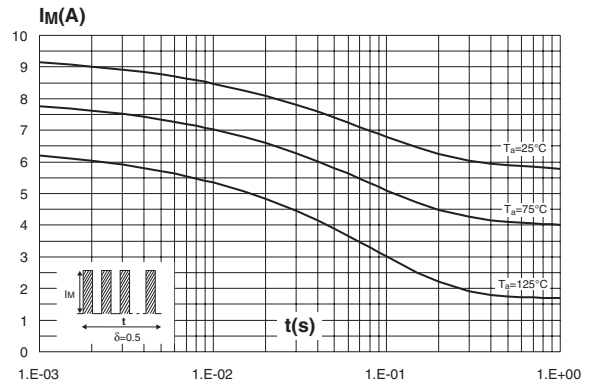


Figure 7: Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy printed circuit board, e(Cu)=35µm, recommended pad layout) (SMA)

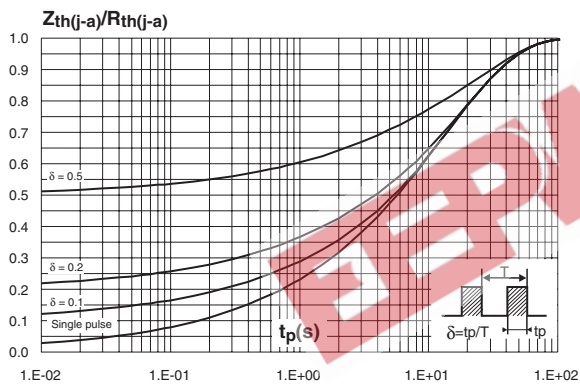


Figure 8: Relative variation of thermal impedance junction to ambient versus pulse duration (DO-41)

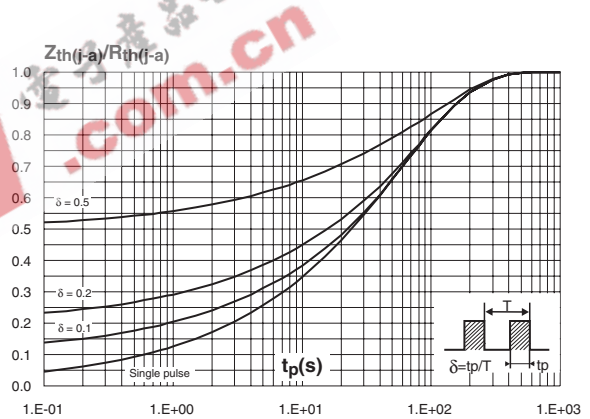


Figure 9: Reverse leakage current versus reverse voltage applied (typical values)

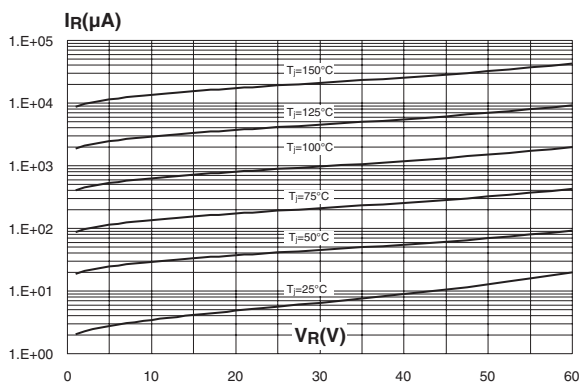


Figure 10: Junction capacitance versus reverse voltage applied (typical values)

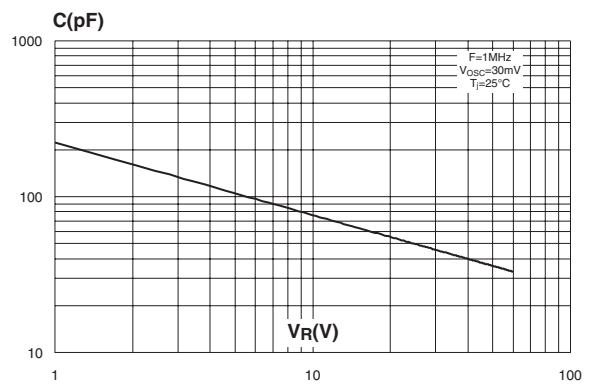


Figure 11: Forward voltage drop versus forward current (maximum values, low level)

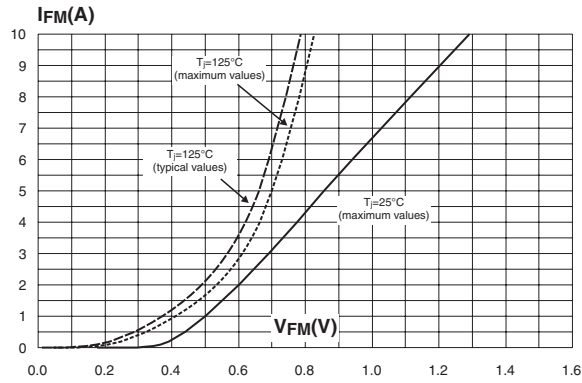


Figure 12: Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: 35µm) (SMA)

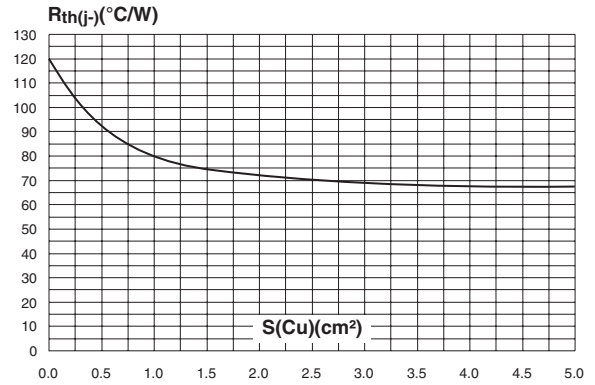


Figure 13: Thermal resistance versus lead length (DO-41)

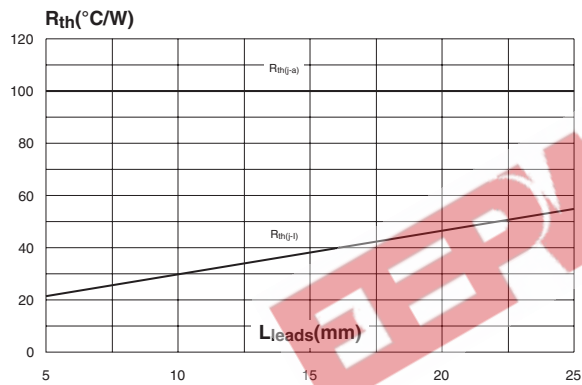
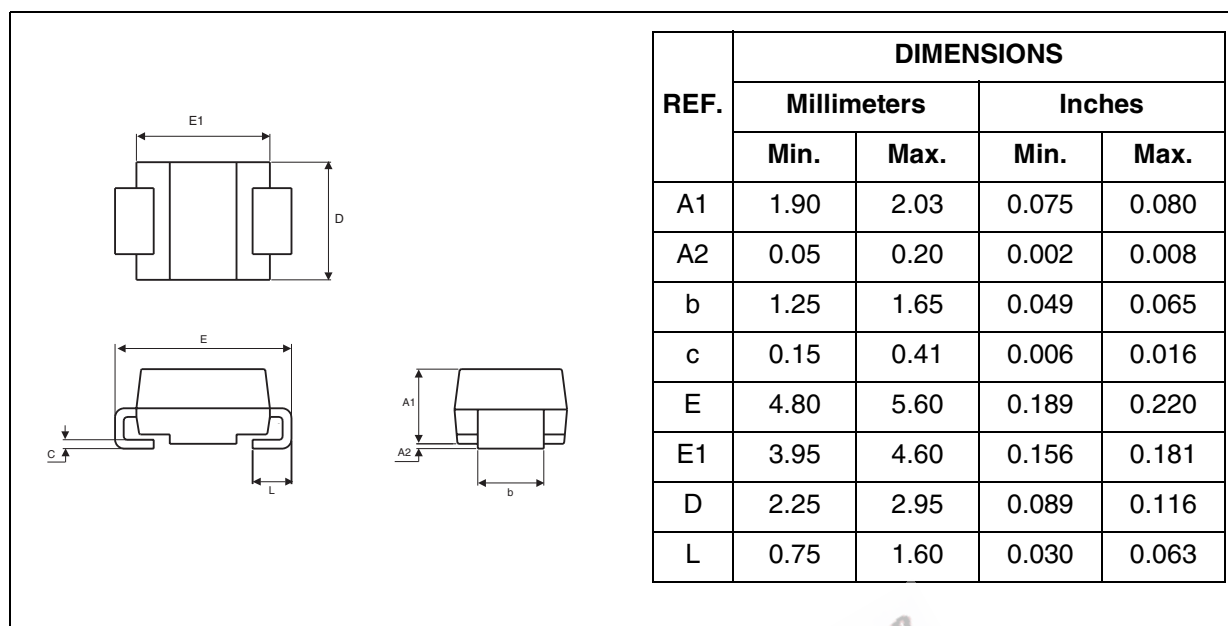
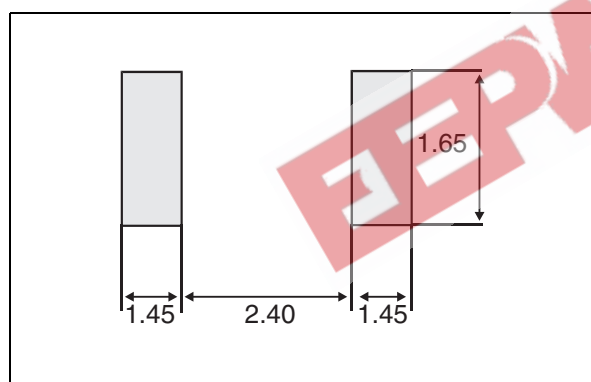


Figure 14: SMA Package Mechanical Data

Figure 15: SMA Foot Print Dimensions
(in millimeters)

STPS2L60

Figure 16: DO-41 Package Mechanical Data

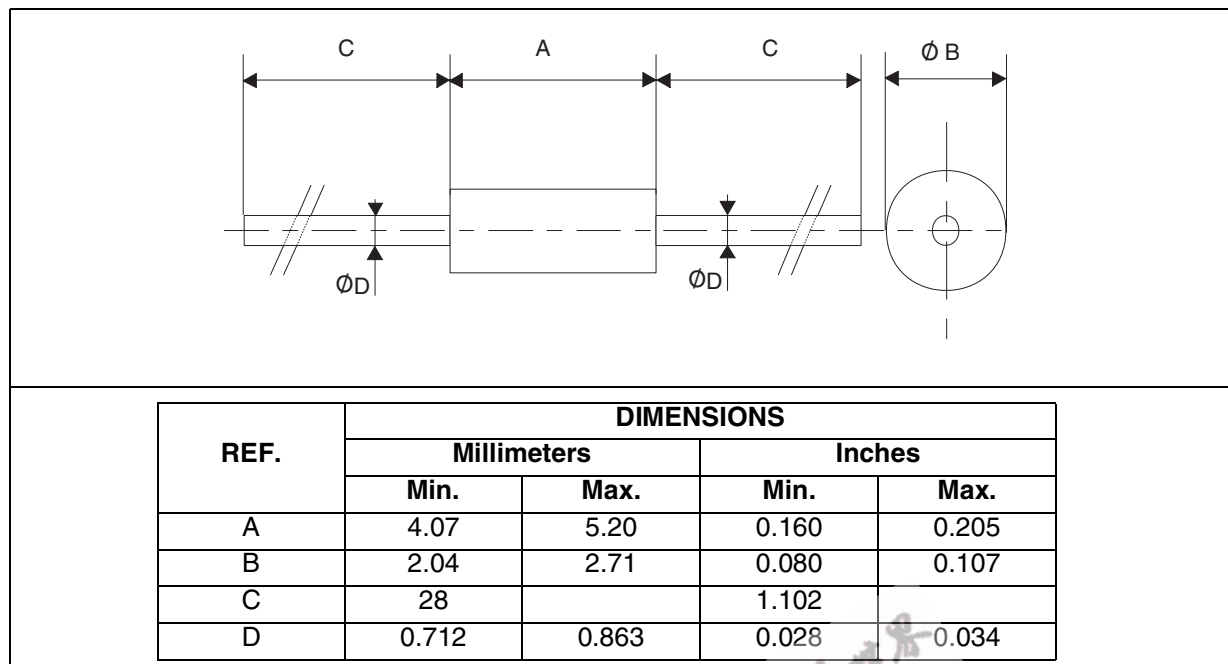


Table 6: Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS2L60A	S26	SMA	0.068 g	5000	Tape & reel
STPS2L60	STPS2L60	DO-41	0.34 g	2000	Ammopack
STPS2L60RL	STPS2L60	DO-41	0.34 g	5000	Tape & reel

- Band indicates cathode
- Epoxy meets UL94, V0

Table 7: Revision History

Date	Revision	Description of Changes
Jul-2003	2A	Last update.
Aug-2004	3	SMA package dimensions update. Reference A1 max. changed from 2.70mm (0.106inc.) to 2.03mm (0.080).

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